EMLC - Online Event 2021
36th European Mask and Lithography Conference

Tuesday, June 22nd, 2021

Live PANEL SESSIONS with Live Q&A

Panel Session timing is chosen in order to allow live participation worldwide as much as possible.
After the event, Panel presentation slides will be uploaded to: www.emlc-conference.com
Video movies of the Panel Sessions will be uploaded to: www.vistec-semi.com

Panel Session times are indicated in the Central European Summer Time (CEST) zone.

08:00 – 11:00   PART 1

Pacific Time start: June 21st 11:00 PM	Eastern Time start: June 22nd 02:00 AM	Ireland UK start: June 22nd 07:00 AM	CEST Israel start: June 22nd 08:00 AM	Russia Turkey start: June 22nd 09:00 AM	China Taiwan start: June 22nd 02:00 PM	Korea Japan start: June 22nd 03:00 PM

08:00 CEST   　hopin　meeting is opened by VDE-GMM meeting host Ms Hatice Altintas.
In case of questions, contact Ms Claudia Braeuer: claudia.braeuer@vde.com

08:05 – 08:15

Welcome by Uwe Behringer / UBC, EMLC 2021 Chair

08:15 – 09:30   1st EMLC 2021 PANEL on EUV LITHOGRAPHY

Panel Chair: Jo Finders / ASML (The Netherlands)

Panel Co-Chair: Albrecht Ehrmann / Carl Zeiss SMT (Germany)

PANEL TOPIC: EUV Lithography towards 2030.

PANELIST: Gijsbert Rispens / ASML (The Netherlands)
EUV system engineering imaging and resist

PANELIST: Ardavan Niroomand / IMEC (Belgium)
Program director for ASML/IMEC Advanced Patterning Center

PANELIST: Heiko Feldmann / Carl Zeiss SMT (Germany)
Head of Roadmap, initiating technology and product developments for semiconductor manufacturing equipment
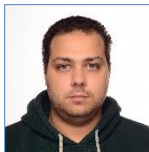
PANELIST: Hazem Mesilhy / Fraunhofer IISB (Germany)
PhD student / researcher, computational lithography, High-NA EUV, mask 3D, optical simulations, multi-objective optimization

PANELIST: Renzo Capelli / Carl Zeiss SMS (Germany)
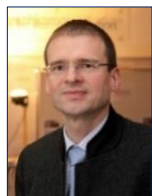*System Engineering, ZEISS Semiconductor Mask Solutions (SMS), EUV mask metrology*

PANELIST: Jan van Schoot/ASML (The Netherlands)
Director EUV System Engineering

09:30 – 11:00   2nd EMLC 2021 PANEL on EUV MASK TOPICS

Panel Chair: Jan Hendrik Peters / BMBG Consult (Germany)

Panel Co-Chair: Martin Tschinkl / TOPPAN Europe (Germany)

PANEL TOPIC: Readiness of the mask and lithography infrastructure for current and future EUV (phase shift masks and anamorphic) and suitable tools for mask making in EUV

PANELIST: Tilmann Heil / Carl Zeiss SMS (Germany)
Mask Repair; Mask Qualification; EUV: scaling for advanced nodes, High NA, phase shifting masks

PANELIST: Eelco van Setten / ASML (The Netherlands)
EUV imaging - specifically High-NA, mask contribution to imaging or EPE

PANELIST: Takahiro Onoue / HOYA (Japan)
EUV materials, especially PSM, transparent backside

PANELIST: Kei Hattori / SHIBAURA (Japan)
EUV clean and etch, material properties, layout requirements

PANELIST: Joost Bekaert / IMEC (Belgium)
Stitching and black borders, CNT pellicle, contour metrology, OPC

PANELIST: Don Gun Lee / ESOL (South Korea)
EUV phase shift measurements, microscope, pellicle transmission

11:00 – 14:30   CASUAL MEETINGS during the BREAK

Between the morning and afternoon session you have the possibility to casually meet with your peers in the [meeting space](#) wonder.me provided by the conference committee.

Just join with audio and video connected, move around and join in small discussion circles. You will be automatically placed in a zoom like video chat with your colleagues within these circles.

14:30 – 17:30   PART 2

Pacific Time	Eastern Time	Ireland UK	CEST Israel	Russia Turkey	China Taiwan	Korea Japan
start:	start:	start:	start:	start:	start:	start:
June 22nd	June 22nd	June 22nd	June 22nd	June 22nd	June 22nd	June 22nd
05:30 AM	08:30 AM	01:30 PM	02:30 PM	03:30 PM	08:30 PM	09:30 PM

14:30 CEST   🌀 hopin meeting is opened by VDE-GMM meeting host Ms Hatice Altintas.
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14:35 – 14:45

Welcome by Uwe Behringer / UBC, EMLC 2021 Chair

14:45 – 16:00   3rd EMLC 2021 PANEL on MANUFACTURING DATA ANALYTICS

Panel Chair: Bertrand Le Gratiet / ST Microelectronics (France)

Panel Co-Chair: Serap Savari / Texas A&M University (USA)

PANEL TOPIC: Turning Data into Silicon: The Digital Transformation of the Wafer Fabrication Processes

PANELIST: Philippe Leduc / STMicroelectronics (Singapore)
Principal Engineer in Applied Mathematics & Scientific Computing, Technical advisor for the Manufacturing Data Analytics program
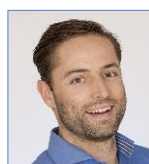
PANELIST: Benjamin Lenz / Infineon (Germany)
Infineon Technologies AG Head of Operations AI and Analytics
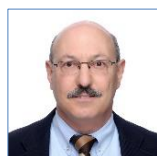
PANELIST: Harry J Levinson / HJL Lithography (USA)
HJL lithography, LLC provides consulting and training services in lithography and lithography process control

PANELIST: Jelle Nije / ASML (The Netherlands)
Sr product manager, Advanced Analytics portfolio enabling fast time to insight and optimize decision making
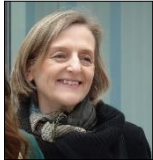
PANELIST: Clemens Utzny / KLA - QONIAC (Germany)
Qoniac provides revolutionary lithography & patterning optimization for the semiconductor industry

16:00 – 17:15   **4ᵗʰ EMLC 2021 PANEL on CAREER OPTIONS for YOUNG SCIENTISTS in the SEMICONDUCTOR LITHOGRAPHY INDUSTRY**

Panel Chair: Andreas Erdmann / Fraunhofer IISB (Germany)

Panel Co-Chair: Ines Stolberg / Vistec Electron Beam (Germany)

PANEL TOPIC: Career opportunities for university young scientists and engineers in semiconductor lithography and mask industry

PANELIST: Rene Carpaij / ASML (The Netherlands)
Group Lead EUV Imaging

PANELIST: Jan Hoentschel / GLOBALFOUNDRIES (Germany)
Director Integration & Technology

PANELIST: Bertrand Le Gratiet / STMicroelectronics (France)
Fellow Lithography / Metrology

PANELIST: Hans-Jürgen Stock / Synopsys Munich (Germany)
Manager Research and Prototyping

PANELIST: Michael Woittennek / X-Fab (Germany)
Manager Process Engineering

PANELIST: Holger Jennewein / Carl Zeiss SMT (Germany)
Director Optics Metrology

17:15 – 17:30   Final Remarks by Uwe Behringer / UBC, EMLC 2021 Chair

and

Announcement of EMLC 2022 conference at KU Leuven, Belgium, Monday, June 20th - Wednesday, June 22nd, 2022, and (optional) Visit at IMEC on Thursday, June 23rd, 2022

Co-operation Partners

Sponsors of the EMLC 2021